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Patent Number: WO9002216

Publication date: 1990-03-08

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Requested Patent: WO9002216

Application Number: WO1988US02950 19880825

Priority Number(s): WO1988US02950 19880825

IPC Classification: C23C14/34; C23C14/54

EC Classification: C23C14/32A

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Equivalents: JP2836876B2, JP3502215T

Abstract

A machine for covering a substrate (Fig. 14, 540) by means of both cathodic arc plasma deposition (CAPD) (Fig. 2) and magnetron sputtering (Fig. 1) without breaking vacuum in a single chamber (Fig. 14, 421). A computer system monitors (Fig. 3, 403, 405) and controls all coating process parameters to coat in any sequence multiple thin film layers using either the CAPD or magnetron sputtering process. A rotating substrate table (Fig. 14, 470) used in conjunction with internal and external targets coats both sides of the substrate simultaneously.